

# **MULTI-INNO TECHNOLOGY CO., LTD.**

## LCD MODULE SPECIFICATION

Model: MI0350B1T

Revision	1.7
Engineering	
Date	
Our Reference	

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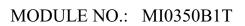
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## **REVISION RECORD**

REV NO.	REV DATE	CONTENTS	REMARKS
0.1	2010-4-13	First release	Preliminary
1.0	2010-5-15	Full spec	/
1.1	2010-5-25	Update the interface description	P.11
1.2	2010-7-14	Update the drawing	P.5
1.3	2011-2-20	Update the drawing	P.5
1.4	2011-3-18	Update the drawing	P.5
1.5	2011-3-20	Update the module area	P.4
1.6	2011-4-19	Add the interface type	P.4
1.7	2011-5-26	Update the module power consumption Update the input current	P.4 P.6



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- PRECAUTIONS FOR USING LCD MODULES
- PACKING SPECIFICATION
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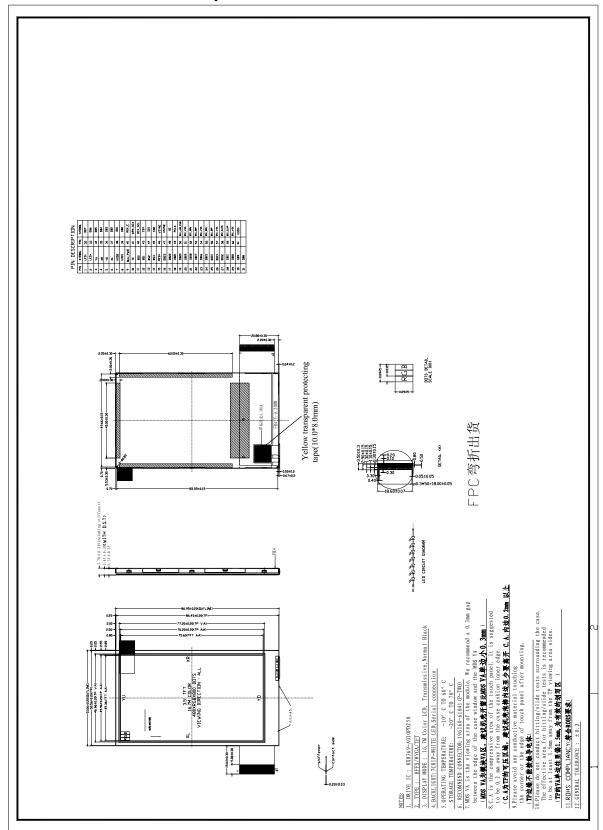


## **■ GENERAL INFORMATION**

Item	Contents	Unit
LCD type	HFFS/WVGA/TFT/TRANSMISSIVE	/
Recommended Viewing Direction	Full viewing angle	O' Clock
Module area (W $\times$ H $\times$ T)	51.06×86.95×3.70	mm <sup>3</sup>
Viewing area (W×H)	46.96×77.20	mm <sup>2</sup>
Active area (W×H)	45.36×75.60	mm <sup>2</sup>
Number of Dots	480RGB×800	/
Pixel pitch (W × H)	0.0945×0.0945	mm <sup>2</sup>
Driver IC	HX8369-A010PD250	/
Interface Type	MPU/SPI+RGB/MIPI interface	/
Input voltage	3.3	V
Module Power consumption	547	mw
Colors	16.7M	/
Backlight Type	LED	/



## ■ EXTERNAL DIMENSIONS





MODULE NO.: MI0350B1T

## ■ ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Min	Max	Unit
Supply voltage for logic	VDD2/VDD3	-0.3	5.5	V
Supply voltage for I/O interface	VDD1	-0.3	3.6	V
Operating temperature	Тор	-10	60	°C
Storage temperature	TST	-20	70	°C
Humidity	RH	-	90%(Max60 °C)	RH

## ■ ELECTRICAL CHARACTERISTICS

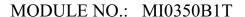
## **DC CHARACTERISTICS**

Parameter	Symbol	Min	Тур	Max	Unit
Supply voltage for logic	VDD2/VDD3	2.3	2.8/3.3	4.8	V
I/O power supply	VDD1	1.65	1.8/2.8/3.3	3.3	V
Input Current	Idd	-	32.04	64.08	mA
Input voltage 'H' level	VIH	0.7VDD1	-	VDD1	V
Input voltage 'L' level	VIL	-0.3	-	0.3VDD1	V
Output voltage 'H' level	VOH	0.8VDD1	-	-	V
Output voltage 'L' level	VOL	-	-	0.2VDD1	V

## ■ BACKLIGHT CHARACTERISTICS

Item	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward voltage	Vf	21	22.4	23.8	V	If=15mA
Luminance	Lv	4000	4400	4800	cd/m <sup>2</sup>	Ta=25°C
Number of LED	-	-	7	-	Piece	-
Connection mode	S	-	Serial	-	-	-

Using condition: constant current driving method If=15mA(+/-10%).





#### ■ ELECTRO-OPTICAL CHARACTERISTICS

Item	Symbol	Condition	Min	Тур	Max	Unit	Remark	Note
Response time	Tr+ Tf		-	35	53	ms	Fig.1	4
Contrast ratio	Cr	$\theta=0^{\circ}$	282	563	-		FIG 2.	1
Luminance uniformity	δ WHITE	Ø=0° Ta=25°C	82	91	-	%	FIG 2.	3
Surface Luminance	Lv	1a-25 C	158	197	-	cd/m <sup>2</sup>	FIG 2.	2
		Ø = 90°	70	80	-	deg	FIG 3.	
Viewing angle	θ	Ø = 270°	70	80	-	deg	FIG 3.	6
range	Ө	$\varnothing = 0$ °	70	80	-	deg	FIG 3.	
		Ø = 180°	70	80	-	deg	FIG 3.	
	Red x		0.5757	0.6257	0.6757	-		
	Red y		0.3006	0.3506	0.4006	-		
	Green x	$\theta=0^{\circ}$	0.2817	0.3317	0.3817	-		
CIE (x, y)	Green y	Ø=0°	0.5561	0.6061	0.6561	-	FIG 2.	5
chromaticity	Blue x	Ta=25°C	0.0919	0.1419	0.1919	-	FIG 2.	3
	Blue y	1 a-25 C	0.0251	0.0751	0.1251	-		
	White x		0.2233	0.2833	0.3433	-		
	White y		0.2404	0.3004	0.3604	-		

Note1. Contrast Ratio(CR) is defined mathematically by the following formula. For more information see FIG 2.:

ContrastRatio =  $\frac{\text{AverageSurface Luminance with all white pixels (P 1, P2, P 3, P4, P5)}}{\text{Average SurfaceLuminance with all black pixels (P1, P2, P 3, P4, P5)}}$ 

Note2. Surface luminance is the LCD surface from the surface with all pixels displaying white. For more information see FIG 2.

Lv = Average Surface Luminance with all white pixels (P1, P2, P3,P4, P5)

Note3. The uniformity in surface luminance (δ WHITE) is determined by measuring luminance at each test position 1 through 5, and then dividing the maximum luminance of 5 points luminance by minimum luminance of 5 points luminance. For more information see FIG 2.

$$\delta \text{ WHITE} = \frac{\text{Minimum Surface Luminance with all white pixels } (P_1, P_2, P_3, P_4, P_5)}{\text{Maximum Surface Luminance with allwhite pixels } (P_1, P_2, P_3, P_4, P_5)}$$

Note4. Response time is the time required for the display to transition from White to black(Rise Time, Tr) and from black to white(Decay Time, Tf). For additional information see FIG 1..

Note5. CIE (x, y) chromaticity ,The x,y value is determined by screen active area position 5. For more information see FIG 2.

Note6. Viewing angle is the angle at which the contrast ratio is greater than 2. For TFT module the conrast ratio is greater than 10. The angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the LCD surface. For more information see FIG 3.

Note7. For Viewing angle and response time testing, the testing data is base on Autronic-Melchers's ConoScope. Series Instruments. For contrast ratio, Surface Luminance, Luminance uniformity and CIE, the testing data is base on TOPCON's BM-5 photo detector.

Note8. For TFT transmissive module, Gray scale reverse occurs in the direction of panel viewing angle.



#### FIG.1. The definition of Response Time

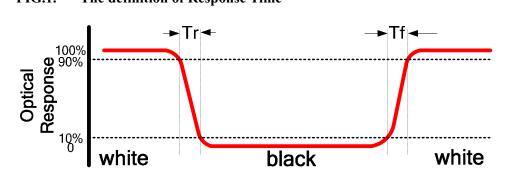


FIG.2. Measuring method for Contrast ratio, surface luminance, Luminance uniformity, CIE (x, y) chromaticity

A:5 mm

B:5 mm

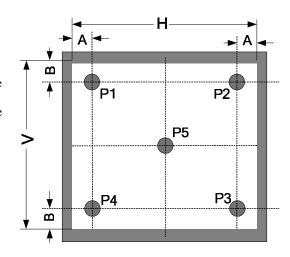
H,V: Active Area

Light spot size ∅=5mm, 500mm distance from the

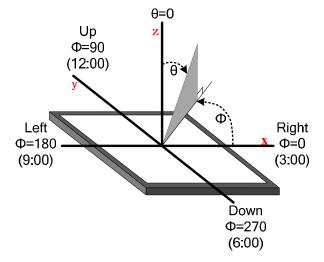
LCD surface to detector lens

measurement instrument is TOPCON's luminance

meter BM-5



#### FIG.3. The definition of viewing angle



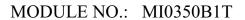


## ■ INTERFACE DESCRIPTION

Pin NO.	Symbol	I/O or connect to	Description	When not in use	
1	LED-	LED driver	LED CATHODE		
2	LED+	LED driver	LED ANODE	-	
3	YU	TP driver	Touch panel coordinate in the up side of envisage drawing.	-	
4	XR	TP driver	Touch panel coordinate in the right side of envisage drawing.	-	
5	YD	TP driver	Touch panel coordinate in the down side of envisage drawing.	-	
6	XL	TP driver	Touch panel coordinate in the left side of envisage drawing.	-	
7	VDD2	Power supply	A power supply for the analog power. VDD2=2.3 to 4.8V VDD2 input level should be same as VDD3 input level to avoid the level-mismatching at internal level shifter circuit.TYPE:2.8/3.3V	-	
8	VDD1	Power supply	A power supply for the I/O circuit. VDD1=1.65 to 3.3V. TYPE:1.8V/2.8/3.3V	-	
9	BLU_PWM	О	Backlight on/fff control pin. If use CABC function, the pin can connect to external LED driver IC. The output voltage range=0 to VDD1.	OPEN	
10	TE	О	Serves TE (Tearing Effect ) pin on MPU interface.	OPEN	
11	BS0	I Host processor			
12	BS1	I Host processor	MPU interface mode selection signal.Must be connected to GND or VDD1.For the	-   -	
13	BS2	I Host processor	details, please refer to <b>NOTE1</b> .	-   -	
14	BS3	I Host processor			
15	RESX	I Hostprocessor/reset circuit	Reset pin. Setting either pin low initializes the LSI. Must be reset after power is supplied (Must be connected to GND or VDD1).	-	
16~39	DB[23:00]	I/O Host processor	Data bus. For the connection condition of the MPU & RGB interface mode, please refer to NOTE1 and NOTE2	OPEN	
40	RDX_E	I Host processor	DBI Type-A: 0: Read/Write disable, 1: Read / Write enable. DBI Type-B: Serves as a read signal and read data at the low level.	OPEN or VDD1	
41	WRX_DCX	I Host processor	DBI Type-B mode: Serves as a write signal and write data at the low level. DBI Type-A mode: 0: Read/Write disable, 1: Read / Write enable.	OPEN or VDD1	



42	DCX_SCL	I Host processor	DBI Type-A/B: Data / Command Selection pin DBI Type-C: it servers as SCL (Serial Clock)	OPEN or VDD1
43	CSX	I Host processor	Chip select signal. Low: chip can be accessed; High: chip cannot be accessed.	GND or VDD1
44	SDI	I Host processor	Serial data input pin in serial interface operation.	OPEN
45	SDO	I Host processor	Serial data output. Let it to open in MPU interface mode.	OPEN
46	VSYNC	I Host processor	Frame synchronization signal. Serves VS signal pin on RGB interface. (Input pad).	GND or VDD1
47	HSYNC	I Host processor	Line synchronization signal.	GND or VDD1
48	DE	I Host processor	A data enable signal in RGB I/F mode. Has to be fixed to GND level in MPU interface mode.	GND
49	PCLK	I Host processor	Pixel clock signal.	GND or VDD1
50	DSI_LDO_ENB	I VDD1 or GND	DSI I/F:Control signal of DSI_LDO. The default setting of DSI_LDO_ENB is Low. High: Disable the DSI_LDO;Low: Eable the DSI_LDO.  MDDI I/F:Control signal of MDDI_LDO. The default setting of MDDI_LDO_ENB is Low.High: Disable the MDDI _LDO;Low: Eable the MDDI _LDO.It must be connected to VDD1 or GND. (latch type)	-
51	DSI_VSS	Power supply	MIPI DSI analogy ground. DSI_VSS=0V. When using the COG method, connect to VSSA on the FPC to prevent noise.	1
52	DSI_D0N	I/O	MIPI-DSI interface: MIPI-DSI Data differential signal input pins. (Data lane 0)	GND
53	DSI_D0P	Host processor	MDDI interface: High Speed Interface Data differential signal input pins. (Data lane 1) Connect to a terminal resistance (100) between MDDI_D1P and MDDI_D1N.	GND
54	DSI_VSS	Power supply	MIPI DSI analogy ground. DSI_VSS=0V. When using the COG method,connect to VSSA on the FPC to prevent noise.	-
55	DSI_D1N	I/O	MIPI-DSI interface:MIPI-DSI Data differential signal input pins. (Data lane 1) MDDI interface: High Speed Interface Data	GND
56	DSI_D1P	Host processor	differential signal input pins. (Data lane 0) Connect to a terminal resistance (100) between MDDI D0P and MDDI D0N.	GND
57	DSI_VSS	Power supply	MIPI DSI analogy ground. DSI_VSS=0V. When using the COG method,connect to VSSA on the FPC to prevent noise.	-





58	DSI_CLKN	ī	MIPI-DSI interface:MIPI-DSI CLOCK differential signal input pins. MDDI interface: High Speed Interface	GND
59	DSI_CLKP	Host processor	clock differential signal input pins.Connect to a terminal resistance (100) between MDDI STBP and MDDI STBN.	GND
60	DSI_VSS	Power supply	MIPI DSI analogy ground. DSI_VSS=0V. When using the COG method,connect to VSSA on the FPC to prevent noise.	-
61	VDD3	Power supply	A power supply for the logic power, DC/DC converter VDD3=2.3 to 4.8V.TYPE:2.8/3.3V	-

## Note1:

ote1			-			
elect	the MF	U inter	face m	ode as listed below:	i	I
BS3	BS2	BS1	BS0	MPU interface mode	DB pins	Display mode
0	0	0	0	DBI TYPE-A 8-bit (CLK-E)	DB23-DB8: Unused, DB7-DB0: Data	Type 1
0	0	0	1	DBI TYPE-A 9-bit (CLK-E)	DB23-DB9:Unused, DB8-DB0: Data	Type 1
0	0	1	0	DBI TYPE-A 16-bit (CLK-E)	DB23-DB16: Unused, DB15-DB0: Data	Type 1
0	0	1	1	DBI TYPE-A 18-bit (CLK-E)	DB23-DB18: Unused, DB17-DB0: Data	Type 1
0	1	0	0	DBI TYPE-B 8-bit	DB23-DB8: Unused DB7-DB0: Data	Type 1
0	1	0	1	DBI TYPE-B 9-bit	DB23-DB9:Unused, DB8-DB0: Data	Type 1
0	1	1	0	DBI TYPE-B 16-bit	DB23-DB16: Unused, DB15-DB0: Data	Type 1
0	1	10	. ((	DBI TYPE-B 18-bit	DB23-DB18: Unused, DB17-DB0: Data	Type 1
1	0	6	0	DSI (Command mode)	DSI_CLKP, DSI_CLKN, DSI_D0P, DSI_D0N, DSI_D1P, DSI_D1N	Туре
(1)	3)	0,20		3-wire serial + MDDI interface (note 1)	MDDI_STBP, MDDI_STBN, MDDI_D0P, MDDI_D0N, MDDI_D1P, MDDI_D1N,	(7.)
1	0	1	0	DBI TYPE-B 24-bit	DB23-DB0: Data	Type 1
1	0	1	1	5	-	-
1	1	0	0	DSI (Video mode)	DSI_CLKP, DSI_CLKN, DSI_D0P, DSI_D0N, DSI_D1P, DSI_D1N	Туре
1	1	0	1	DPI/DBI TYPE-C Option 1	SDA DB23-DB0	Туре
1	1	1	0	DPI/DBI TYPE-C Option 2	SDA, DB23-DB0	Туре
1	1	1	1	DPI/DBI TYPE-C Option 3	SDA, DB23-DB0	Туре

Pixel format (RGB565 / RGB666 / RGB888) is selected by DCS command (0x3Ah)
Note 1: 3-wire serial Interface only active on MDDI / Hibernation mode.
Must be connected to VSSD or VDD1.



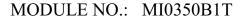
MODULE NO.: MI0350B1T

## Note2:

Data bus	Used	Unused
16-bit bus	DB21-17, DB13-8, DB5-1	DB23-22, DB116-14, DB7-6, DB0
18-bit bus	DB21-16, DB13-8, DB5-0	DB22-21, DB15-14, DB7-6
24-bit bus	DB23-D0	- 1

## ■ REFERENCE APPLICATION CIRCUIT

Please consult our technical department for detail information.





## ■ RELIABILITY TEST CONDITIONS

No.	Test Item	<b>Test Condition</b>	Inspection after test
1	High Temperature Storage	70±2℃/200 hours	
2	Low Temperature Storage	-20±2°C/200 hours	
3	High Temperature Operating	60±2°C/120 hours	
4	Low Temperature Operating	$-10\pm2$ °C/120 hours	
5	Temperature Cycle	$-10\pm2$ °C~25~60 $\pm2$ °C × 10cycles (30min.) (5min.) (30min.)	Inspection after 2~4hours storage at
6	Damp Proof Test	$50$ °C $\pm 5$ °C $\times 90$ %RH/120 hours	room temperature, the
7	Vibration Test	Frequency: 10Hz~55Hz~10Hz Amplitude: 1.5mm, X, Y, Z direction for total 3hours (Packing condition)	sample shall be free from defects: 1.Air bubble in the LCD; 2.Sealleak;
8	Dropping test	Drop to the ground from 1m height, one time, every side of carton. (Packing condition)	3.Non-display; 4.missing segments; 5.Glass crack;
9	ESD test	Voltage:±8KV R: 330Ω C: 150pF Air discharge, 10time	<ul><li>6.Current Idd is twice higher than initial value.</li><li>7. The surface shall be</li></ul>
10	Hitting test	1,000,000 times in the same point, Hitting pad: tip R3.75 mm, Silicone rubber, Hardness:40 deg.; Load: 2.45N; Hitting speed: Twice/sec; Electric load: None; Test area should be at 1.8 mm inside of touch panel view area	free from damage.  8.Linearity must be no more than 1.5% by the linearity tester.  9.The Electrical characteristics requirements shall be
11	Pen sliding durability test	100, 000 times minimum Hitting pad: tip R0.8 mm Plastic pen; Load:1.47N; Sliding speed: 60 mm/sec; Electric load: None Test area should be at 1.8 mm inside of touch panel view area	satisfied.

#### Remark:

- 1. The test samples should be applied to only one test item.
- 2. Sample size for each test item is 5~10pcs.
- 3. For Damp Proof Test, Pure water(Resistance  $\geq$  10M $\Omega$ ) should be used.
- 4.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part.
- 5.EL evaluation should be excepted from reliability test with humidity and temperature: Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence EL has
- 6.Failure Judgment Criterion: Basic Specification, Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.



#### ■ INSPECTION CRITERION

This specification is made to be used as the standard acceptance/rejection criteria for Color mobile phone LCM with touch panel.

## 1 Sample plan

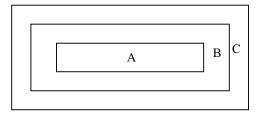
Sampling plan according to GB/T2828.1-2003/ISO 2859-1: 1999 and ANSI/ASQC Z1.4-1993, normal level 2 and based on:

Major defect: AQL 0.65 Minor defect: AQL 1.5

### 2. Inspection condition

Viewing distance for cosmetic inspection is about 30cm with bare eyes, and under an environment of 20~40W light intensity, all directions for inspecting the sample should be within 45° against perpendicular line.

3. Definition of inspection zone in LCD.



Zone A: character/Digit area

Zone B: viewing area except Zone A (ZoneA+ZoneB=minimum Viewing area)

Zone C: Outside viewing area (invisible area after assembly in customer's product)

Fig.1 Inspection zones in an LCD.

Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble for quality and assembly of customer's product.



## 4. Inspection standards

## 4.1 Major Defect

Item No	Items to be inspected	Inspection Standard	Classification of defects
4.1.1	All functional defects	<ol> <li>No display</li> <li>Display abnormally</li> <li>Missing vertical, horizontal segment</li> <li>Short circuit</li> <li>Back-light no lighting, flickering and abnormal lighting.</li> </ol>	
4.1.2	Missing	Missing component	36.
4.1.3	Outline dimension	Overall outline dimension beyond the drawing is not allowed.	Major
4.1.4	linearity	No more than 1.5%	

## **4.2 Cosmetic Defect**

Item No	Items to be inspected	Inspection Standard					assification of defects	
	Clear	For dark/white spot as $\Phi = \frac{(x+y)}{2}$	t, sizeФis defined		x y			
	Spots	1.						
	Black and white Spot	Zor	ne A	cceptable	Qty			
	defect Pinhole,	Size(mm)	A	В	С		Minor	
	Foreign	Ф≤0.1	Igno	ore				
	Particle, polarizer	0.10<Φ≤0.15	2	2				
	Dirt	Dirt $0.15 < \Phi \le 0.20$	1		Ignore			
4.2.1		Ф>0.20	0					
	Clear Spots	2.						
	TP Dirt	Zone	Acc	eptable Qt	у			
	11 Dilt	Size(mm)	A	В	С			
		Ф≤0.1	Ignore				Minor	
		0.10<Φ≤0.15	3		Ignore			
		0.15<Φ≤0.25	2		ignore			
		0.25<Ф	0					



Dim Spots	3.				
Zim spots	2. Zone	Acceptable Qty			
Circle shaped and	Size(mm)	A	В	С	
dim edged	Ф≤0.2	Ignore			Minor
defects	0.20<Φ≤0.40	2		I am a ma	
	0.40<Φ≤0.60		1	Ignore	
	0.60<Ф		0		
				•	

## 4.2. Cosmetic Defect

Item No	Items to be inspected	Inspection Standard						Classification of defects		
	Line defect	Size(mm) Acceptable Qt								
		L(Lengtl	h) W(Width	,		Zone				
	Black line, White line,	E(Ectigu	ii) WWidii	, A	4	В	C			
	Foreign	Ignore	W≤0.02		Igno	re		Minor		
	material on polarizer	L≤3.0	0.02 <w≤0< td=""><td>.03</td><td>2</td><td></td><td></td><td></td></w≤0<>	.03	2					
	4.2.2 Foreign material on	L≤2.0	0.03 < W < 0	.05	1		Ignore			
			0.05 <w< td=""><td>D</td><td>efine a defe</td><td></td><td></td><td></td></w<>	D	efine a defe					
4.2.2		material on	•	_	The line ca condition:	n be seen after r	nobile ph	none	in the	operating
	TP film	siz	size(mm)			table (	Qty			
		L(Length)	W(Width)	zone						
		L(Lengin)	w (widii)	A		В	С			
		Ignore	W≤0.03	Ig	Ignore					
			L≤5.0	0.03 < W < 0.05		3		Ignore		
			0.05 <w< td=""><td>Define as</td><td>s spot d</td><td>lefect</td><td></td><td></td></w<>	Define as	s spot d	lefect				

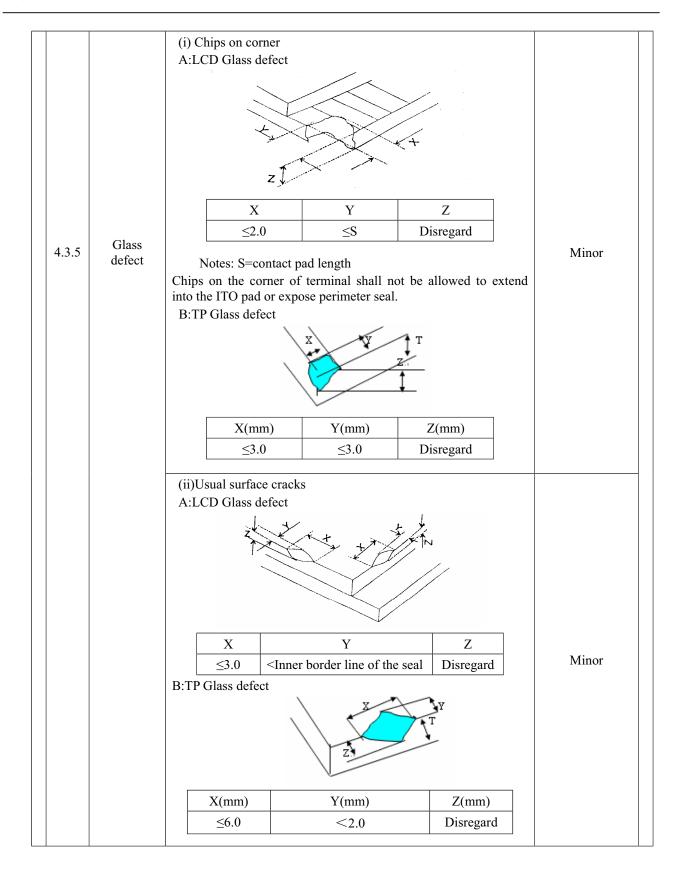


Dim line defect		If the scratch can be seen after mobile phone cover assembling or in the operating condition, judge by the line defect of 4.2.2.  If the scratch can be seen only in non-operating condition or some special angle, judge by the following.  Size(mm)  Acceptable Qty					e line	
4.2.3	Polarizer	Size	(IIIII)		-	one Qty	Minor	Minor
	scratch TP film scratch	L(Length)	W(Width)	A	В	С	-	
		Ignore	Ignore W≤0.03		nore			
		5.0 <l≤10.0< td="">     0.03<w≤0.05< td="">       L≤5.0     0.05<w≤0.08< td=""></w≤0.08<></w≤0.05<></l≤10.0<>			2			
					1	Ignore		
			0.08 < W		0			
		Air bubbles bet	ween glass & pola	rizer				
		2. Zone	2. Zone Acc		le Qty			
	D.L	Size(mm)	A	В		С		
4.2.4	Polarize Air bubble	Ф≤0.2	Ignore	Ignore				Minor
	- III 0 000010	0.20<Φ≤0.30				Iomono		
		0.30<Φ≤0.50	1			Ignore		
		0.50<Ф	0					

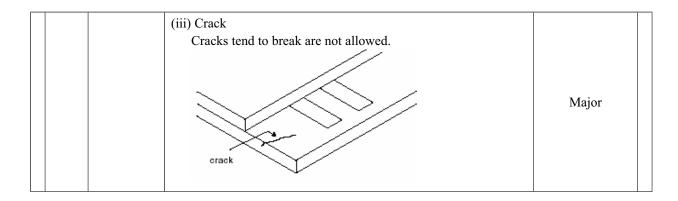
## 4.3. Cosmetic Defect

Item	Items to be	L	Classification of
No	inspected	Inspection Standard	defects









#### 4.4 Parts Defect

4.4	Parts Defect		
Item No	Items to be inspected	Inspection Standard	Classificatio n of defects
	4.4.1 Parts contraposit ion	<ol> <li>Not allow IC and FPC/heat-seal lead width is more than 50% beyond lead pattern.</li> <li>Not allow chip or solder component is off center more than 50% of the pad outline.</li> </ol>	
	4.4.2 SMT	According to the <acceptability assemblies="" electronic="" of=""> IPC-A-610C class 2 standard. Component missing or function defect are Major defect, the others are Minor defect.</acceptability>	
	4.4.3 TP Defect	1、 Pattern font: Pattern fonts are clear and symmetrical, pattern fonts filter lightly are allowed; The fort line is not allow to thinner or thicker than 1/3of normal size, and swing is not more than 0.1mm. the line is smooth and not broken.  图案字体 Pattern font  2、 The wing forward in the side of Visual Area: The length of wing forward inside of the Visual Area: n≤0.2mm; Not excess 3 point, and the distanceD≥20mm。  3、 Film impression:With operation, must be invisibility.  4、 Touch panel knob: if writing function normally,it could be allowed.	



5. Newton ring

Without operation, the color circle of Regularity or Non-regularity from the normal or slope angle of view.

- 1. **Regularity:** The area of the newton ring is less than 1/3 area of the touch panel; and no character affected and line distorted after touch panel lightening. It's ok.
- 2. **Non-regularity**: The area of the Newton ring is less than the 1/2 area of touch panel with lightening. And no character affected and line







#### ■ PRECAUTIONS FOR USING LCD MODULES

### 1 Handing Precautions

- 1.1 The display panel is made of glass and polarizer. As glass is fragile. It tends to become or chipped during handling especially on the edges. Please avoid dropping or jarring. Do not subject it to a mechanical shock by dropping it or impact.
- 1.2 If the display panel is damaged and the liquid crystal substance leaks out, be sure not to get any in your mouth. If the substance contacts your skin or clothes, wash it off using soap and water.
- 1.3 Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary. Do not touch the display with bare hands. This will stain the display area and degraded insulation between terminals (some cosmetics are determined to the polarizer).
- 1.4 The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully. Do not touch, push or rub the exposed polarizers with anything harder than an HB pencil lead (glass, tweezers, etc.). Do not put or attach anything on the display area to avoid leaving marks on it. Condensation on the surface and contact with terminals due to cold will damage, stain or dirty the polarizer. After products are tested at low temperature they must be warmed up in a container before coming in to contact with room temperature air.
- 1.5 If the display surface becomes contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If it is heavily contaminated, moisten cloth with one of the following solvents
  - Isopropyl alcohol
  - Ethyl alcohol

Do not scrub hard to avoid damaging the display surface.

- 1.6 Solvents other than those above-mentioned may damage the polarizer. Especially, do not use the following.
  - Water
  - Ketone
  - Aromatic solvents

Wipe off saliva or water drops immediately, contact with water over a long period of time may cause deformation or color fading. Avoid contact with oil and fats.

- 1.7 Exercise care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by water droplets, moisture condensation or a current flow in a high-humidity environment.
- 1.8 Install the LCD Module by using the mounting holes. When mounting the LCD module make sure it is free of twisting, warping and distortion. In particular, do not forcibly pull or bend the I/O cable or the backlight cable.
- 1.9 Do not attempt to disassemble or process the LCD module.
- 1.10 NC terminal should be open. Do not connect anything.
- 1.11 If the logic circuit power is off, do not apply the input signals.
- 1.12 Electro-Static Discharge Control, Since this module uses a CMOS LSI, the same careful attention should be paid to electrostatic discharge as for an ordinary CMOS IC. To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment
  - Before removing LCM from its packing case or incorporating it into a set, be sure the module and your body have the same electric potential. Be sure to ground the body when handling the LCD modules.
  - Tools required for assembling, such as soldering irons, must be properly grounded. Make certain the AC power source for the soldering iron does not leak. When using an electric screwdriver to attach LCM, the screwdriver should be of ground potentiality to minimize as much as possible any transmission of electromagnetic waves produced sparks coming from the commutator of the motor.
    - To reduce the amount of static electricity generated, do not conduct assembling



and other work under dry conditions. To reduce the generation of static electricity be careful that the air in the work is not too dry. A relative humidity of 50%-60% is recommended. As far as possible make the electric potential of your work clothes and that of the work bench the ground potential.

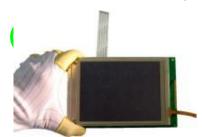
- The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated.
- 1.13 Since LCM has been assembled and adjusted with a high degree of precision, avoid applying excessive shocks to the module or making any alterations or modifications to it.
  - Do not alter, modify or change the shape of the tab on the metal frame.
  - Do not make extra holes on the printed circuit board, modify its shape or change the positions of components to be attached.
    - Do not damage or modify the pattern writing on the printed circuit board.
  - Absolutely do not modify the zebra rubber strip (conductive rubber) or heat seal connector.
  - Except for soldering the interface, do not make any alterations or modifications with a soldering iron.
    - Do not drop, bend or twist the LCM.



## 2 Handling precaution for LCM

- 2.1 LCM is easy to be damaged. Please note below and be careful for handling.
- 2.2 Correct handling:





As above picture, please handle with anti-static gloves around LCM edges.

## 2.3 Incorrect handling:



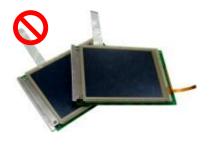
Please don't touch IC directly.



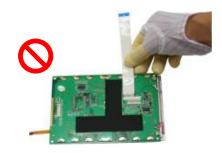
Please don't hold the surface of panel.



Please don't hold the surface of IC.



Please don't stack LCM.



Please don't stretch interface of output, such as FPC cable.



Please don't operate with sharp stick such as pens.



#### 3 Storage Precautions

- 3.1 When storing the LCD modules, the following precaution are necessary.
  - 3.1.1 Store them in a sealed polyethylene bag. If properly sealed, there is no need for the desiccant.
  - 3.1.2 Store them in a dark place. Do not expose to sunlight or fluorescent light, keep the temperature between 0°C and 35°C, and keep the relative humidity between 40%RH and 60%RH.
  - 3.1.3 The polarizer surface should not come in contact with any other objects (We advise you to store them in the anti-static electricity container in which they were shipped).

## 3.2 Others 其它

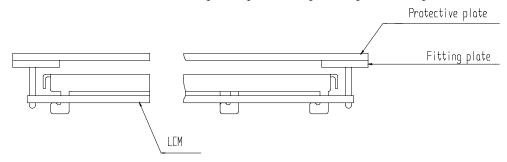
- 3.2.1 Liquid crystals solidify under low temperature (below the storage temperature range) leading to defective orientation or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subject to a low temperature.
- 3.2.2 If the LCD modules have been operating for a long time showing the same display patterns, the display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. A normal operating status can be regained by suspending use for some time. It should be noted that this phenomenon does not adversely affect performance reliability.
- 3.2.3 To minimize the performance degradation of the LCD modules resulting from destruction caused by static electricity etc., exercise care to avoid holding the following sections when handling the modules.
  - 3.2.3.1 Exposed area of the printed circuit board.
  - 3.2.3.2 -Terminal electrode sections.

#### 4 USING LCD MODULES

4.1 Installing LCD Modules

The hole in the printed circuit board is used to fix LCM as shown in the picture below. Attend to the following items when installing the LCM.

4.1.1 Cover the surface with a transparent protective plate to protect the polarizer and LC cell.

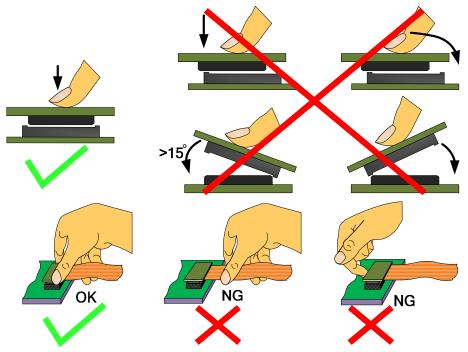


4.1.2 When assembling the LCM into other equipment, the spacer to the bit between the LCM and the fitting plate should have enough height to avoid causing stress to the module surface, refer to the individual specifications for measurements. The measurement tolerance should be  $\pm 0.1$ mm.



## 4.2 Precaution for assemble the module with BTB connector:

Please note the position of the male and female connector position, don't assemble or assemble like the method which the following picture shows





### **4.3** Precaution for soldering the LCM

	Manual soldering	Machine drag soldering	Machine press soldering
No RoHS	290°C ~350°C.	330°C ~350°C.	300°C ~330°C.
Product	Time : 3-5S.	Speed: 15-17 mm/s.	Time : 3-6S.
Froduct			Press: 0.8~1.2Mpa
RoHS	340°C ~370°C.	350°C ~370°C.	330°C ~360°C.
Product	Time : 3-5S.	Speed: 15-17 mm/s.	Time : 3-6S.
Froduct			Press: 0.8~1.2Mpa

- 4.3.1 If soldering flux is used, be sure to remove any remaining flux after finishing to soldering operation (This does not apply in the case of a non-halogen type of flux). It is recommended that you protect the LCD surface with a cover during soldering to prevent any damage due to flux spatters.
- 4.3.2 When soldering the electroluminescent panel and PC board, the panel and board should not be detached more than three times. This maximum number is determined by the temperature and time conditions mentioned above, though there may be some variance depending on the temperature of the soldering iron.
- 4.3.3 When remove the electroluminescent panel from the PC board, be sure the solder has completely melted, the soldered pad on the PC board could be damaged.

#### 4.4 Precautions for Operation

- 4.4.1 Viewing angle varies with the change of liquid crystal driving voltage (VLCD). Adjust VLCD to show the best contrast.
- 4.4.2 It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life. An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- 4.4.3 Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operating temperature.
- 4.4.4 If the display area is pushed hard during operation, the display will become abnormal. However, it will return to normal if it is turned off and then back on.
- 4.4.5 A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit. Usage under the maximum operating temperature, 50%RH or less is required.
- 4.4.6 Input logic voltage before apply analog high voltage such as LCD driving voltage when power on. Remove analog high voltage before logic voltage when power off the module. Input each signal after the positive/negative voltage becomes stable.
- 4.4.7 Please keep the temperature within the specified range for use and storage. Polarization degradation, bubble generation or polarizer peel-off may occur with high temperature and high humidity.

## 4.5 Safety

- 4.5.1 It is recommended to crush damaged or unnecessary LCDs into pieces and wash them off with solvents such as acetone and ethanol, which should later be burned.
- 4.5.2 If any liquid leaks out of a damaged glass cell and comes in contact with the hands, wash off thoroughly with soap and water.



#### 4. 6 Limited Warranty

Unless agreed between Multi-Inno and the customer, Multi-Inno will replace or repair any of its LCD modules which are found to be functionally defective when inspected in accordance with Multi-Inno LCD acceptance standards (copies available upon request) for a period of one year from date of production. Cosmetic/visual defects must be returned to Multi-Inno within 90 days of shipment. Confirmation of such date shall be based on data code on product. The warranty liability of Multi-Inno limited to repair and/or replace on the terms set forth above. Multi-Inno will not be responsible for any subsequent or consequential events.

#### 4.7 Return LCM under warranty

- 4.7.1 No warranty can be granted if the precautions stated above have been disregarded. The typical examples of violations are :
  - 4.7.1.1 Broken LCD glass.
  - 4.7.1.2 PCB eyelet is damaged or modified.
  - 4.7.1.3 -PCB conductors damaged.
  - 4.7.1.4 Circuit modified in any way, including addition of components.
  - 4.7.1.5 PCB tampered with by grinding, engraving or painting varnish.
  - 4.7.1.6 Soldering to or modifying the bezel in any manner.
- 4.7.2 Module repairs will be invoiced to the customer upon mutual agreement. Modules must be returned with sufficient description of the failures or defects. Any connectors or cable installed by the customer must be removed completely without damaging the PCB eyelet, conductors and terminals.

#### ■ PACKING SPECIFICATION

Please consult our technical department for detail information.

#### ■ PRIOR CONSULT MATTER

- 1 For Multi-Inno standard products, we keep the right to change material, process ... for improving the product property without prior notice to our customer.
- 2 For OEM products, if any changes are needed which may affect the product property, we will consult with our customer in advance.
- 3 If you have special requirement about reliability condition, please let us know before you start the test on our samples.